File Edit Tools Windows Help

- Drafts
- Pending
- Active
  - L1: (837) (204/224R).CCLS.
  - L2: (465690) semiconductor or semiconductors
  - L3: (184704) wafer or wafers
  - L4: (140344) 12 and 13
  - L5: (154) 11 and 14
  - L6: (171466) cup or cups
  - L7: (57) 15 and 16
  - L8: (41619) bowl or bowls
  - L9: (35) 15 and 18
  - L10: (11) 19 not 17
  - L11: (51047) electroplats or electrodeposits
  - L12: (112) 14 and 16 and 18 and 111
  - L13: (88) 112 not (17 or 19)
- Failed
- Saved
- Favorites
- Tagged (0)
- UDC
- Queue
- Trash

Search Int Browse 9 zzr Clear

DB: US-PGPUB;USPAT

Default operator OR

l12 not (17 or 19)

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#	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Inventor	U	S	C	P
1	US 20050056537 A1	20050317	35	Planarization of substrates using electrochemical mechanical polishing	204/229.4		Chen, Liang-Yuh et al.	☐	☑	☐	☐
2	US 20050042478 A1	20050224	72	Magnetoresistance effect element, its manufacturing method, magnetic	428/694TM	428/694TS	Okuno, Shiho et al.	☐	☑	☐	☐
3	US 20050006244 A1	20050113	17	Electrode assembly for electrochemical processing of workpiece	205/148	204/275.1	Uzoh, Cyprian E. et al.	☐	☑	☐	☐
4	US 20050000818 A1	20050106	39	Method, chemistry, and apparatus for noble metal electroplating on a	205/102		Graham, Lyndon W. et al.	☑	☐	☐	☐
5	US 20040266327 A1	20041230	31	Conductive polishing article for electrochemical mechanical polishing	451/526		Chen, Liang-Yuh et al.	☑	☐	☐	☐
6	US 20040235406 A1	20041125	163	Abrasive agglomerate coated raised island articles	451/527	51/300	Duescher, Wayne O.	☑	☐	☐	☐
7	US 20040226510 A1	20041118	54	Semiconductor processing apparatus having lift and tilt mechanism	118/719		Hanson, Kyle et al.	☑	☐	☐	☐
8	US 20040222086 A1	20041111	23	Electroplating reactor including back-side electrical contact apparatus	204/297.01	204/297.06; 204/297.08	Woodruff, Daniel J. et al.	☑	☐	☐	☐
9	US 20040188259 A1	20040930	24	Tuning electrodes used in a reactor for electrochemically processing a	205/83	205/123	Wilson, Gregory J. et al.	☑	☐	☐	☐
10	US 20040188257 A1	20040930	19	Methods for processing micro-feature workpieces, patterned structures on	204/478	205/188; 205/205	Klocke, John et al.	☑	☐	☐	☐
11	US 20040169963 A1	20040902	73	Magnetoresistance effect element, its manufacturing method, magnetic	360/324.1	428/693	Okuno, Shiho et al.	☑	☐	☐	☐
12	US 20040134792 A1	20040715	57	Conductive polishing article for electrochemical mechanical polishing	205/640	257/E21.304	Butterfield, Paul D. et al.	☑	☑	☐	☐

3/2005 SN 09/910,481 EPO, JPO, IBM_TDB search

- Drafts
- Pending
- Active
  - L1: (420721) semiconductor or semiconductors
  - L2: (82320) wafer or wafers
  - L3: (19273) electroplats or electrodeposits
  - L4: (26951) cup or cups
  - L5: (10436) bowl or bowls
  - L6: (8) 11 and 12 and 13 and 14
  - L7: (463283) 11 or 12
  - L8: (1) 17 and 13 and 14 and 15
  - L9: (37) 17 and 13 and 14
  - L10: (1) 17 and 13 and 15
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17 and 13 and 15

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